

## Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	$I_D$
-30V	6mΩ@-10V	-60A
	9mΩ@-4.5V	

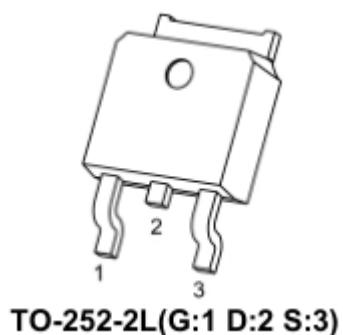
## Feature

- $V_{DS} = -30V, I_D = -60A$
- $R_{DS(ON)} < 8m\Omega$  @  $V_{GS} = -10V$   $R_{DS(ON)} < 13m\Omega$  @  $V_{GS} = -4.5V$
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Excellent package for good heat dissipation
- Pb free terminal plating
- RoHS compliant
- Halogen free

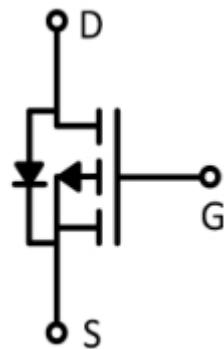
## Application

- High side switch for full bridge converter
- DC/DC converter for LCD display

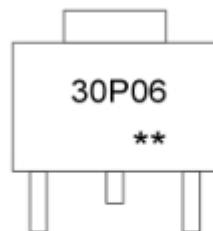
## Package



## Circuit diagram



## Marking



30P06 : Product code  
 \*\* : Week code.

## Absolute maximum ratings

( $T_a=25^\circ\text{C}$  unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	-30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	-60	A
Drain Current-Continuous( $T_C=100^\circ\text{C}$ )		-42	
Drain Current-Pulsed <sup>(1)</sup>	$I_{DM}$	-240	A
Maximum Power Dissipation	$P_D$	110	W
Single pulse avalanche energy <sup>(5)</sup>	$E_{AS}$	450	mJ
Thermal Resistance, Junction-to- Case <sup>(2)</sup>	$R_{\theta JC}$	1.34	$^\circ\text{C}/\text{W}$
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 175	$^\circ\text{C}$

## Electrical characteristics

( $T_A=25^\circ\text{C}$ , unless otherwise noted)

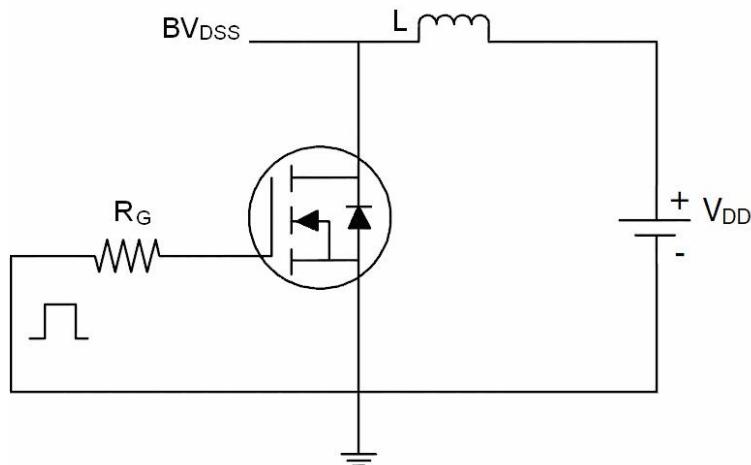
Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{(\text{BR})\text{DSS}}$	$V_{GS} = 0\text{V}, I_D = -250\mu\text{A}$	-30			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = -30\text{V}, V_{GS} = 0\text{V}$			-1	$\mu\text{A}$
Gate-Source Leakage	$I_{GSS}$	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$			$\pm 100$	$\mu\text{A}$
Gate-Source Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	-1	-1.5	-2.5	V
Drain-Source On-Resistance	$R_{DS(\text{on})}$	$V_{GS} = -10\text{V}, I_D = -20\text{A}$		6	8	$\text{m}\Omega$
		$V_{GS} = -4.5\text{V}, I_D = -15\text{A}$		9	13	
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{DS} = -15\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$		4320		pF
Output Capacitance	$C_{oss}$			534		
Reverse Transfer Capacitance	$C_{rss}$			493		
Total Gate Charge	$Q_g$	$V_{DS} = -15\text{V}, I_D = -15\text{A}, V_{GS} = -10\text{V}$		45		nC
Gate-Source Charge	$Q_{gs}$			8		
Gate-Drain Charge	$Q_{gd}$			12		
<b>Switching Characteristics</b>						
Turn-on Delay Time	$T_{d(on)}$	$V_{DD} = -15\text{V}, I_D = -15\text{A}, V_{GS} = -10\text{V}, R_{GEN} = 2.5\Omega$		19		nS
Turn-on Rise Time	$T_r$			15		
Turn-off Delay Time	$T_{d(off)}$			65		
Turn-off Fall Time	$T_f$			36		
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage	$V_{SD}$	$V_{GS} = 0\text{V}, I_s = -55\text{A}$			-1.2	V

### Note:

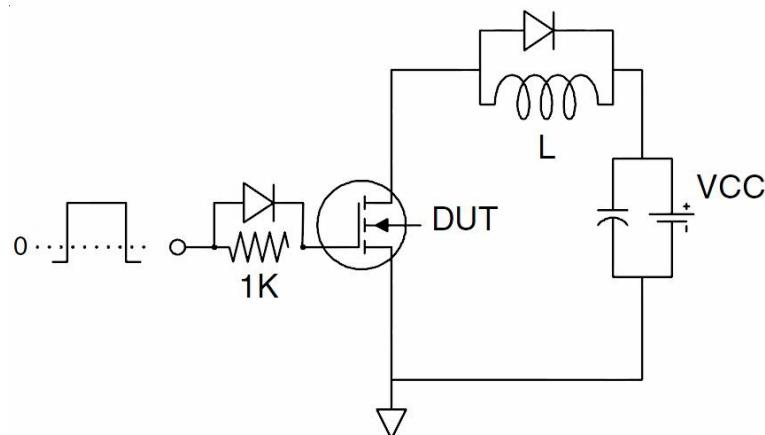
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production
5. E<sub>AS</sub> condition:  $T_j = 25^\circ\text{C}, V_{DD} = -15\text{V}, V_G = -10\text{V}, L = 0.5\text{mH}, R_g = 25\Omega$

## Test Circuit

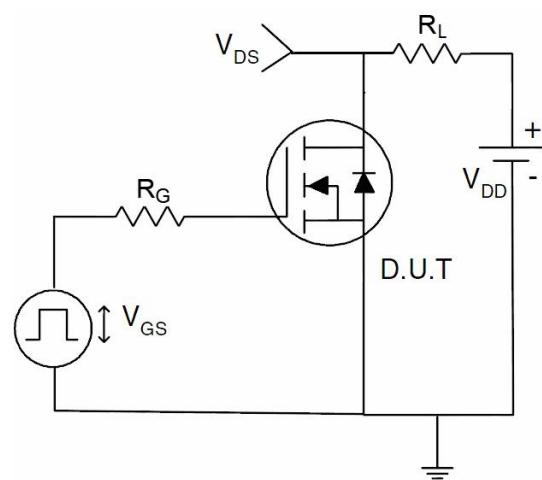
- EAS Test Circuits



- Gate Charge Test Circuit

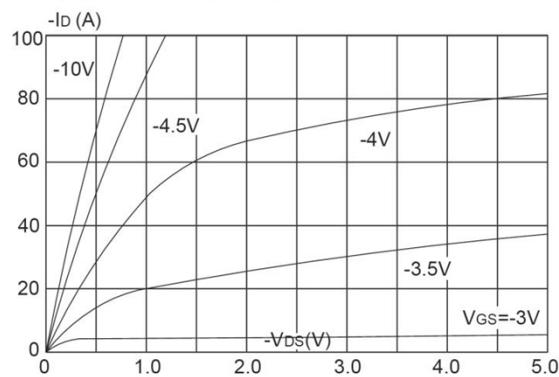


- Switch Time Test Circuit

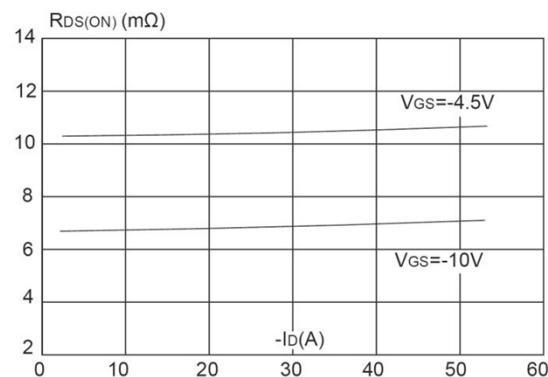


## Typical Characteristics

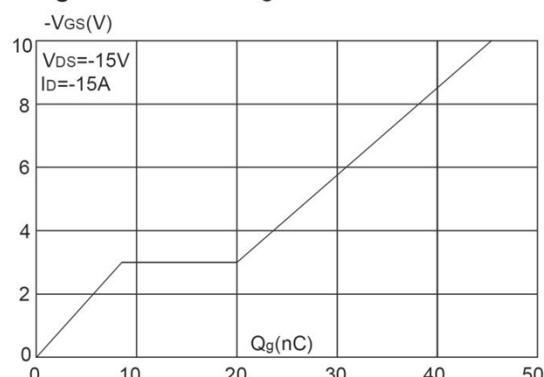
**Figure1:** Output Characteristics



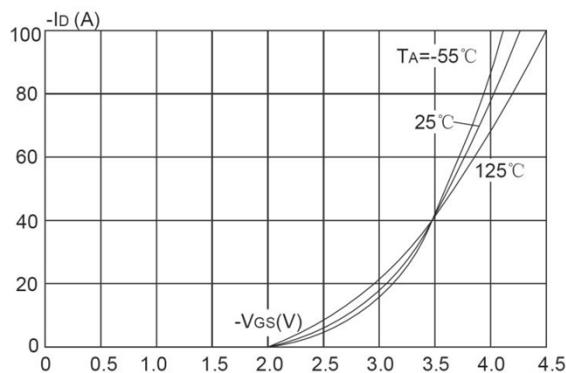
**Figure 3:** On-resistance vs. Drain Current



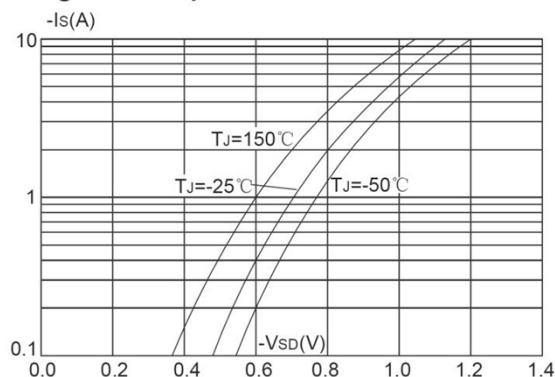
**Figure 5:** Gate Charge Characteristics



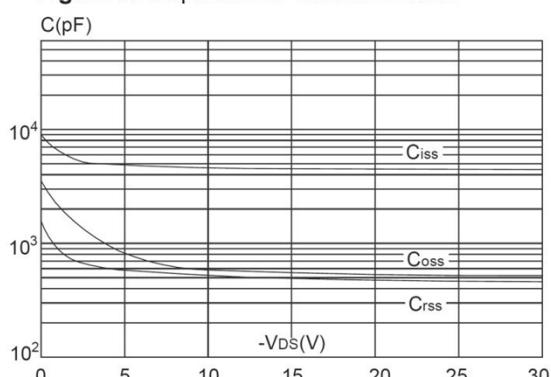
**Figure 2:** Typical Transfer Characteristics



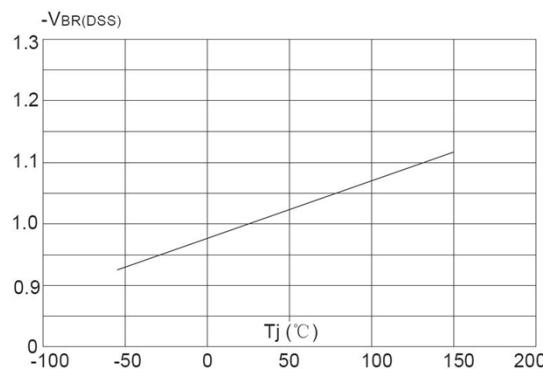
**Figure 4:** Body Diode Characteristics



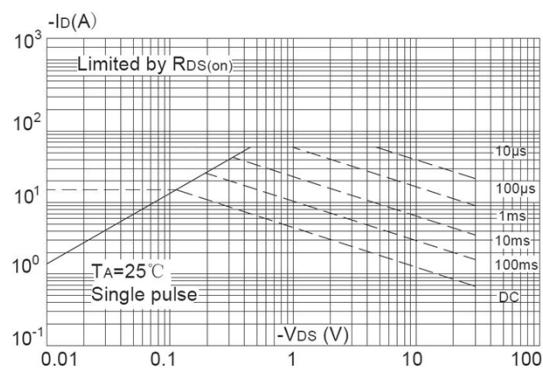
**Figure 6:** Capacitance Characteristics



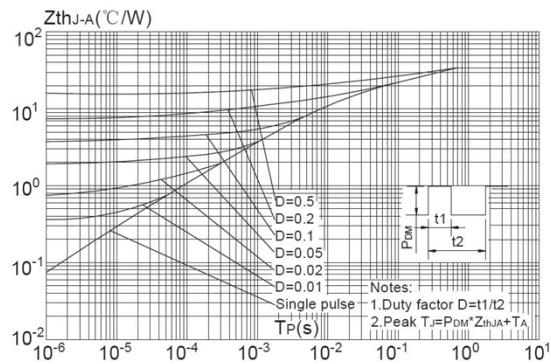
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



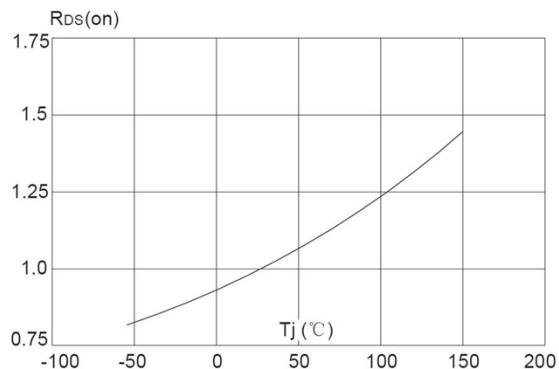
**Figure 9:** Maximum Safe Operating Area



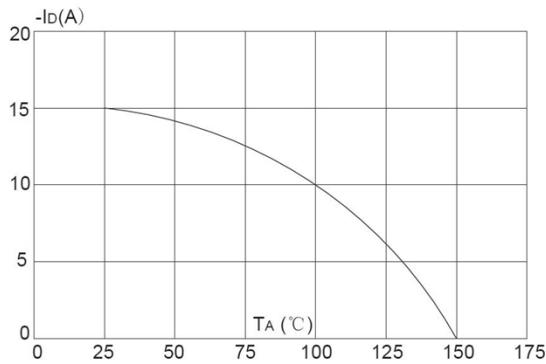
**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



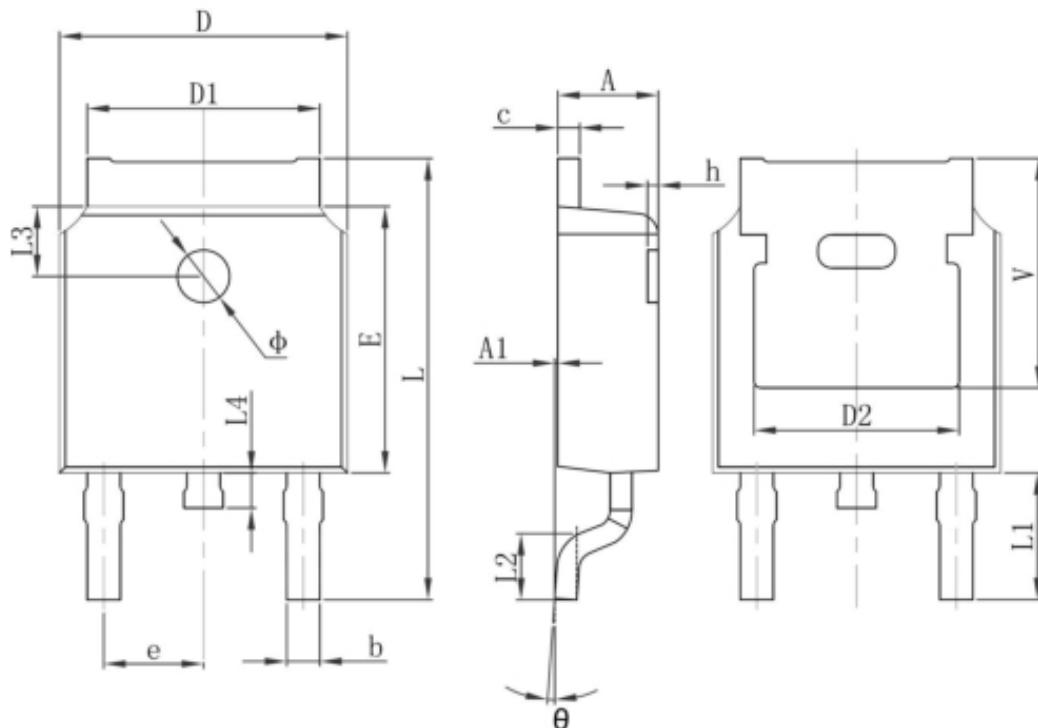
**Figure 8:** Normalized on Resistance vs. Junction Temperature



**Figure 10:** Maximum Continuous Drain Current vs. Ambient Temperature



## TO-252 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 REF.		0.190 REF.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 REF.		0.114 REF.	
L2	1.400	1.700	0.055	0.067
L3	1.600 REF.		0.063 REF.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 REF.		0.211 REF.	